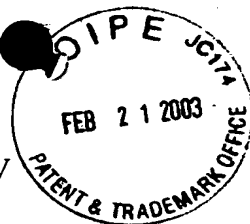


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IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF:

Hisako AOYAMA et al.

SERIAL NO.: 09/558,053

CPA FILED: July 8, 2002

FOR: PROCESS FOR FABRICATING
A METAL WIRING AND METAL
CONTACT IN A SEMICONDUCTOR
DEVICE

:

: GROUP ART UNIT: 2823

:

: EXAMINER: Julio J. MALDONADO

:

SUBSTITUTE AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

RECEIVED
FEB 24 2003
TECHNOLOGY CENTER 2800

Responsive to the Office Action dated August 30, 2002 and the Communication dated
February 10, 2003, please amend the above-identified application as follows:

IN THE CLAIMS

Please amend the claims as shown in the marked-up copy to read as follows:

29. (Four Times Amended) A process of fabricating a semiconductor device
comprising the steps of:

forming a first insulating film on a semiconductor substrate;

forming a second insulating film on said first insulating film, said second insulating
film being made of a material different from that of the first insulating film and having a
thickness smaller than that of the first insulating film;